## 2SC2988

### Silicon NPN Epitaxial Planar Type

RF Power Amplifier

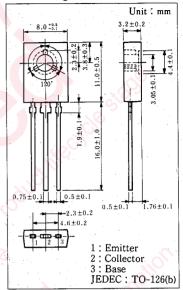
#### ■ Features

- Power output 1.8W on VHF band (f=175MHz)
- High gain 10dB

#### ■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Collector-base voltage	$V_{CBO}$	36	V
Collector-emitter voltage	V <sub>CEO</sub>	16	V
Emitter-base voltage	V <sub>EBO</sub>	3	V
Peak collector current	I <sub>CP</sub>	1	A
Collector current	$I_{\mathbf{C}}$	0.5	.A
Collector power dissipation (Tc=25°C)	Pc	5	w w
Junction temperature	. T <sub>j</sub>	150	°C
Storage temperature	$T_{\rm stg}$	-55~+150	°C

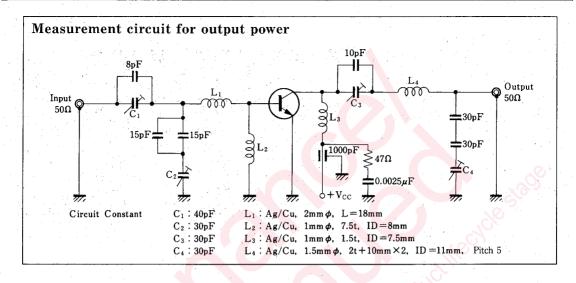
#### ■ Package Dimensions

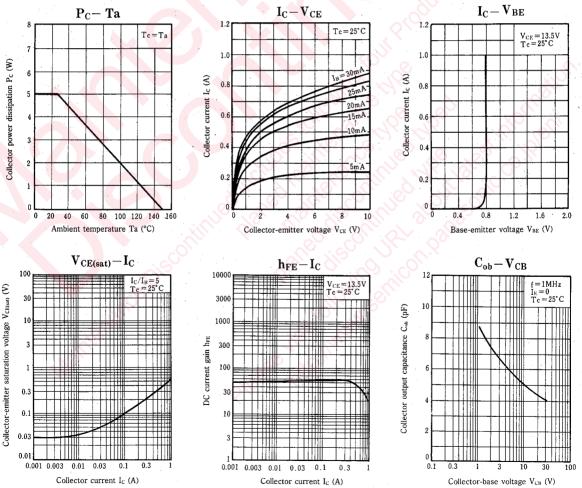


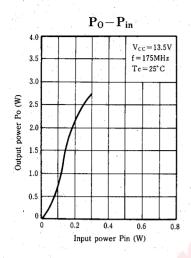
#### ■ Electrical Characteristics (Tc=25°C)

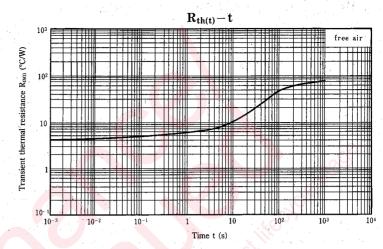
Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = 20V, I_E = 0$	0	XO3	10	μA
Emitter cutoff current	$h_{FE}$	$V_{CE} = 13.5 V, I_{C} = 200 mA^*$	20	50-	9	
Transition frequency	$f_{T}$	$V_{CB} = 10V$ , $I_E = -100 \text{mA}^*$ , $f = 200 \text{MHz}$	600	1000		MHz
Collector output capacitance	Cob	$V_{CB} = 10V, I_E = 0, f = 1MHz$	10	6	10	pF
Overall efficiency characteristics	$P_0$	$V_{CC} = 13.5V$ , $P_{in} = 0.2W$ , $f = 175MHz$	1.8	2.2		W
Output power	ηс	$V_{CC} = 13.5V$ , $P_{in} = 0.2W$ , $f = 175MHz$	600	50		%

<sup>\*</sup>パルス測定









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